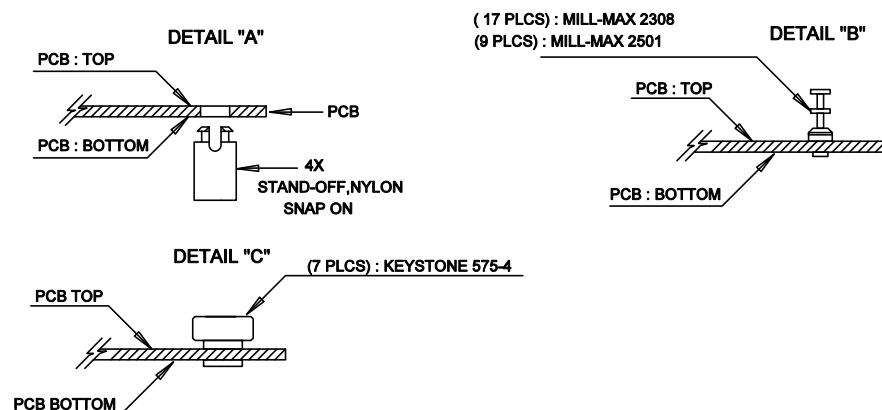
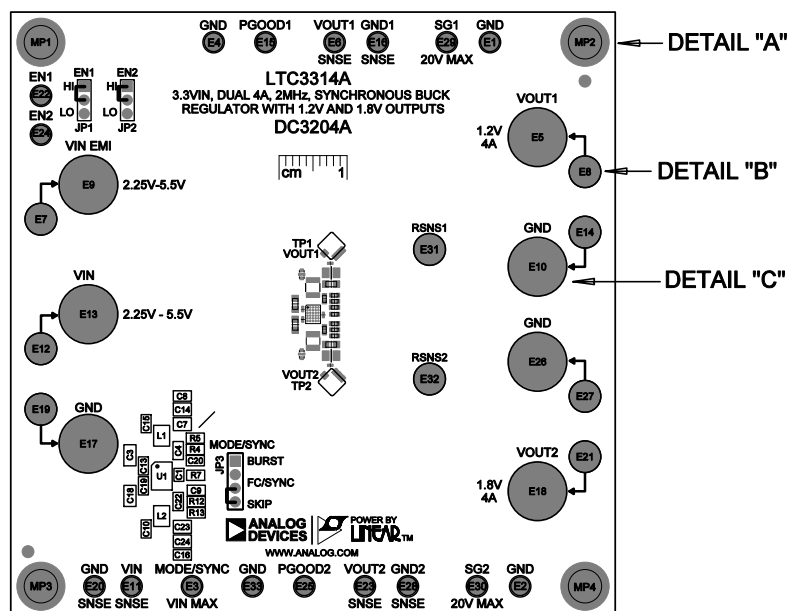




ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	02	PRODUCTION	WL	11-23-24

**NOTES: UNLESS OTHERWISE SPECIFIED**

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY REFLOW PROFILE SHALL BE IN ACCORDANCE WITH J-STD-020 WITH MAXIMUM SOLDER TEMPERATURE OF 250 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS  
LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER.  
MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUT-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. APPLY ASSEMBLY STAMP OR QA STAMP TO BOTTOM OF BOARD (UNSHOWY AREA).
7. INSTALL TURRETS, STAND-OFFS AS SHOWN BELOW:
8. APPLY DEMO S/N AT AREA ON BOTTOM SIDE AS SHOWN ON SHEET 2.



APPROVALS		 <b>ANALOG DEVICES</b>		 <b>POWER BY LINEAR™</b>	
PCB DES	NC	FOR ADI CUSTOMER USE ONLY			
APP ENG	WL	<b>TITLE: TOP ASSEMBLY DRAWING</b> <b>3.3VIN, DUAL 4A, 2MHz, SYNCHRONOUS BUCK</b> <b>REGULATOR WITH 1.2V AND 1.8V OUTPUTS</b>			
		SIZE	IC NO.	LTC3314A	REV.
		N/A		DEMO CIRCUIT 3204A	02
SCALE = NONE					SHT 1 OF 1